

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yoshikazu Higami</td> <td>07/09/2013</td> </tr> <tr> <td>Naoyuki Okita</td> <td>07/13/2013</td> </tr> <tr> <td>Shingo Matsushima</td> <td>07/22/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yoshikazu Higami	07/09/2013	Naoyuki Okita	07/13/2013	Shingo Matsushima	07/22/2013		
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<table border="1"> <tr> <td>Name:</td> <td>Tokyo University of Science Foundation</td> </tr> <tr> <td>Street Address:</td> <td>1-3, Kagurazaka, Shinjuku-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>162-8601</td> </tr> </table>		Name:	Tokyo University of Science Foundation	Street Address:	1-3, Kagurazaka, Shinjuku-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	162-8601
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: 3124740448 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 3124746300 Email: docket@marshallip.com Correspondent Name: Marshall, Gerstein & Borun LLP Address Line 1: 233 S. Wacker Dr. Address Line 2: Suite 6300 Address Line 4: Chicago, ILLINOIS 60606</p>											
ATTORNEY DOCKET NUMBER:	30162/47689										
NAME OF SUBMITTER:	Janis Wilson										
Signature:	/Janis Wilson/										

Date:

07/30/2013

Total Attachments: 2

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ASSIGNMENT

Serial No: 13/982,541 (US Nat'l Phase of PCT/JP2012/052565)

Filed: January 27, 2012

Title: METHOD OF TREATING ISCHEMIA/REPERFUSION INJURY

For \$10.00 (Ten Dollars) and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned hereby assign to TOKYO UNIVERSITY OF SCIENCE FOUNDATION of 1-3, Kagurazaka, Shinjuku-ku, Tokyo 162-8601 Japan (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for letters patent of the United States, executed by the undersigned on,

July 9, 13 and 22, 2013

and in said application and any and all other applications, both in the United States and in other countries, which the undersigned may file or be named as an inventor, either solely or jointly with others, on said invention or improvements, and in any and all letters patent of the United States and other countries, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorize and request the Commissioner for Patents to issue said letters patent to said Assignee.

The undersigned hereby authorize and request that the attorneys of record in said application insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrant themselves to be the owners of the interest herein assigned and to have the right to make this assignment and further warrant that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned except in favor of Assignee.

For said consideration the undersigned hereby agree, upon the request and at the expense of said Assignee, its successors and assigns, to execute any and all applications on said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any letters patent that may be granted upon any and all of said applications, and any and all applications and other documents for letters patent in other countries on said invention or improvements, that said Assignee, its successors or assigns, may deem necessary or expedient, and for said consideration the undersigned further agree upon the request of said Assignee, its successors or assigns, in the event of any application or letters patent assigned herein becoming involved in Interference or Opposition, to cooperate to the best of the ability of the undersigned with said Assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said letters patent, both in the United States and in other countries, and vest all rights therein hereby conveyed in said Assignee, its successors and assigns, whereby said letters patent will be held and enjoyed by said Assignee, its successors and assigns, to the full end of the term for which said letters patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

MARSHALL, GERSTEIN & BORUN LLP, 233 S. Wacker Drive, Suite 6300, Sears Tower, Chicago, Illinois 60606-6357

Executed this 9 day of July, 2013

Yoshikazu HIGAMI

Typed name of inventor

Kazuyuki Higami 7/9/2013
Signature of inventor

Executed this 13 day of July, 2013

Naoyuki OKITA

Typed name of inventor

Naoyuki Okita 7/13/2013
Signature of inventor

Executed this 22 day of July, 2013

Shingo MATSUSHIMA

Typed name of inventor

Shingo Matsushima 7/22/2013
Signature of inventor

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